

ESD-ACF/PI Series

OLB Bonding Cushion Sheet

Technical Data

Product Description

Applies to the ACF bonding process.
 Thermal conductivity, heat resistance, and release characteristics is excellent.
 Teflon sheets are one-time use, but this product is doing everything possible, composite sheet.

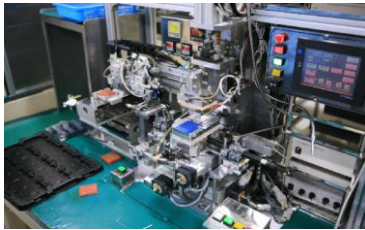
Construction



Complex Silicone layer
Flame Resistance Polyimide film

Features

1. Thermal conductivity
2. Release characteristics
3. Heat resistance : 380°C



Application

- LCD, LED, PDP TV industry
- Mobile part
- Heat transfer sheet
- Heat resistance release sheet

Physical Property

Properties		
Thermal conductivity	W/mK	1.0W/mK
Insulation	Ωcm	10^{13}
Surface flatness	Pressure sensitive paper	good
Number of Uses	Number	>30
Specific gravity	-	1.6
Thickness	mm	0.05~0.3